

BLIGHT

DATASHEET

SMD-Top view LEDs 67-21SYGC/S349/TR8



Features

- P-LCC-2 package.
- Inner reflector and white package.
- · Optical indicator.
- · Colorless clear resin
- Wide viewing angle 120°.
- High performance.
- · Soldering methods: IR reflow soldering.
- · Precondition: Bases on JEDEC J-STD 020D Level 3
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free .(Br<900ppm,Cl<900ppm,Br+Cl<1500ppm)

Applications

- Switches, symbol, mobile phone, digital camera and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Amusement equipment.
- · General applications.
- Optical indicator.



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Super Yellow Green	Water Clear

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	l _F	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	l _{FP}	60	mA
Power Dissipation	Pd	60	mW
Junction Temperature	Tj	115	$^{\circ}\!\mathbb{C}$
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\mathbb{C}$
Storage Temperature	Tstg	-40 ~ + 90	$^{\circ}\!\mathbb{C}$
ESD	ESD _{HBM}	2000	V
Soldering Temperature	T _{sol}	Reflow Soldering : 260 Hand Soldering : 350 °C	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	45		112	mcd	I _F =20mA
Viewing Angle	2 0 _{1/2}		120		deg	I _F =20mA
Peak Wavelength	λр		575		nm	I _F =20mA
Dominant Wavelength	λd	568		573	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		15		nm	I _F =20mA
Forward Voltage	V _F	1.70	2.10	2.40	V	I _F =20mA
Reverse Current	I _R			10	μΑ	V _R =5V

Notes:

- 1. Tolerance of Luminous Intensity: ±11%
- 2. Tolerance of Dominant Wavelength: ±1nm
- 3. Tolerance of Forward Voltage: ±0.1V



Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
P1	45	57	- mcd	
P2	57	72		I _F =20mA
Q1	72	90		IF=ZUIIIA
Q2	90	112		

Bin Range of Dom. Wavelength

Bin Code	Min.	Max.	Unit	Condition
1	568	571		I _F =20mA
2	571	573	nm	IF=ZUIIIA

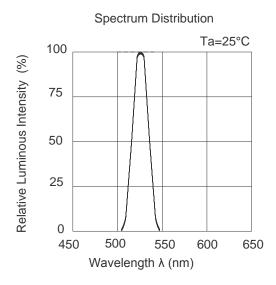
Notes:

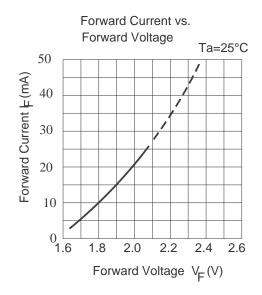
- 1. Tolerance of Luminous Intensity: ±11%
- 2. Tolerance of Dominant Wavelength: ±1nm
- 3. Tolerance of Forward Voltage: ±0.1V

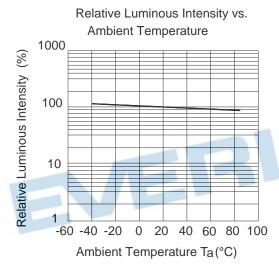


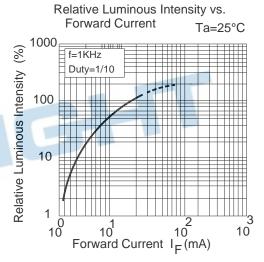


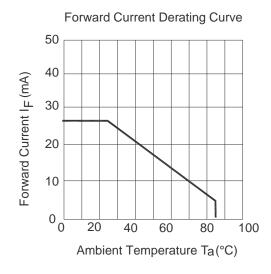
Typical Electro-Optical Characteristics Curves

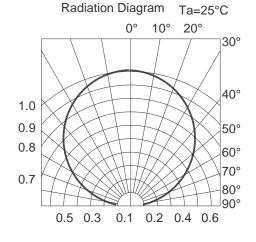






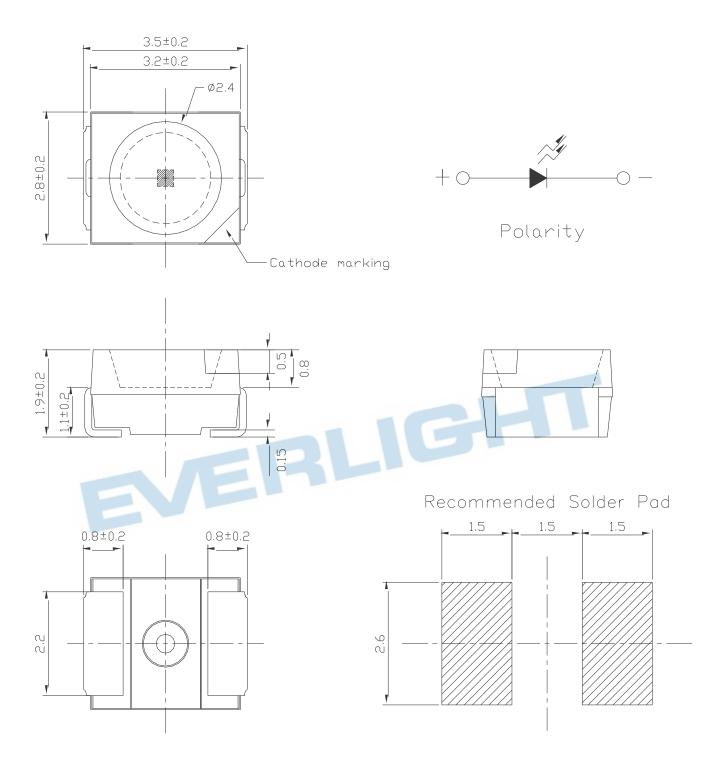








Package Dimension

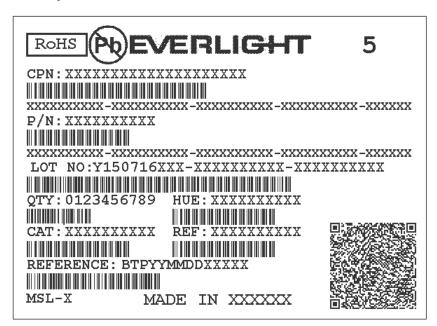


Note: Tolerances unless mentioned ±0.1mm. Unit = mm



Moisture Resistant Packing Materials

Label Explanation

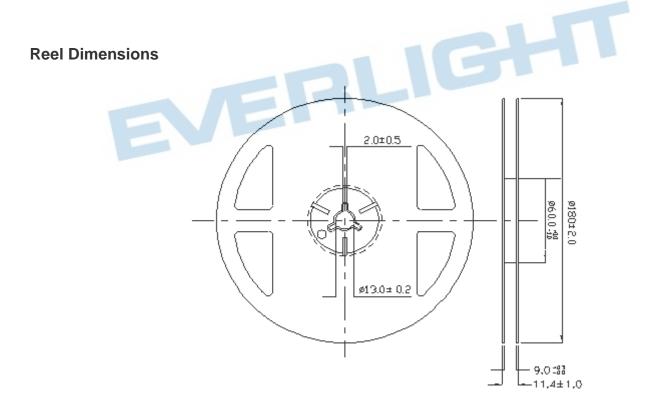


· CPN: Customer's Product Number

P/N: Product NumberQTY: Packing Quantity

CAT: Luminous Intensity RankHUE: Dom. Wavelength RankREF: Forward Voltage Rank

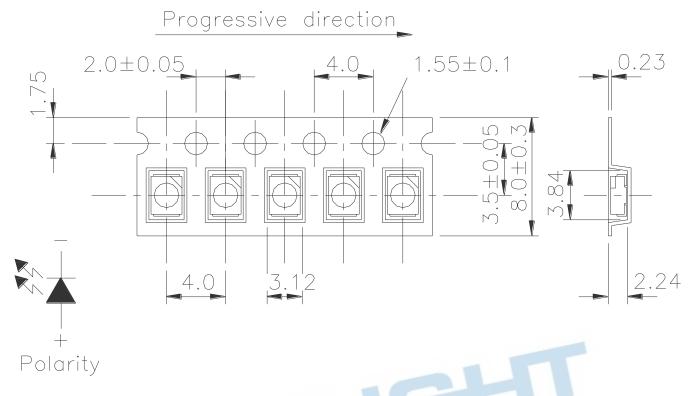
· LOT No: Lot Number



Note: Tolerance unless mentioned is ±0.1mm; Unit = mm



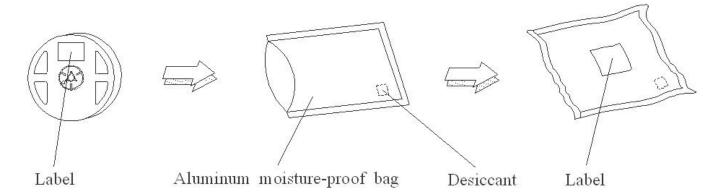
Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel



Note:

Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process

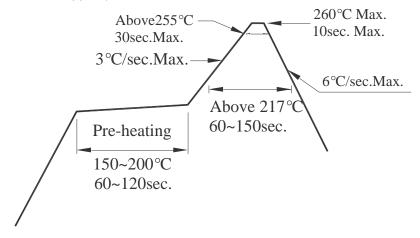




Precautions for Use

1. Over-current-proof

1.1 Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).



2. Storage

- 2.1 Moisture proof bag should only be opened immediately prior to usage.
- 2.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.
- 2.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 2.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

3. Soldering Condition

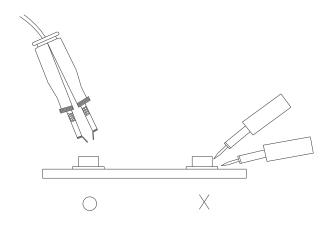
- 3.1 Pb-free solder temperature profile
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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